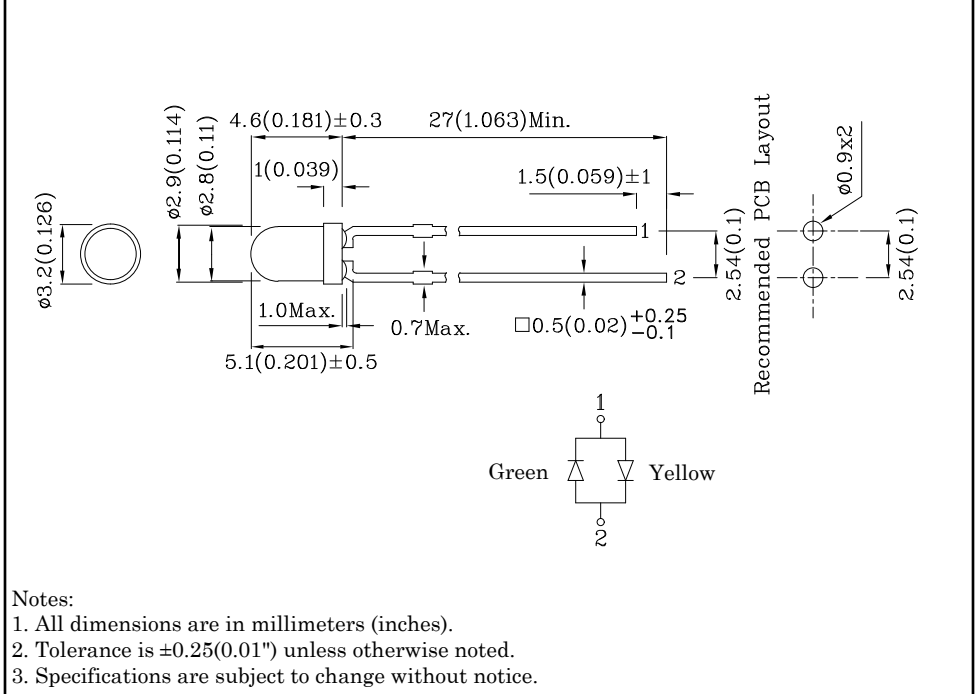


Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant



Package Schematics



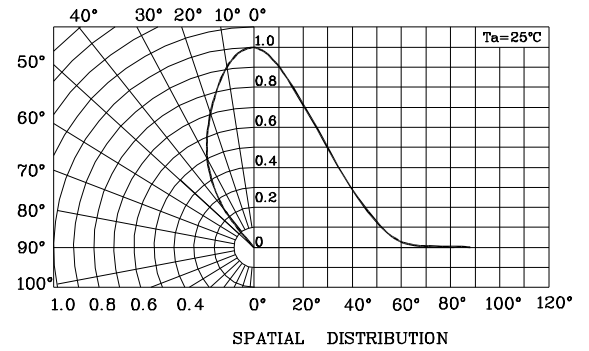
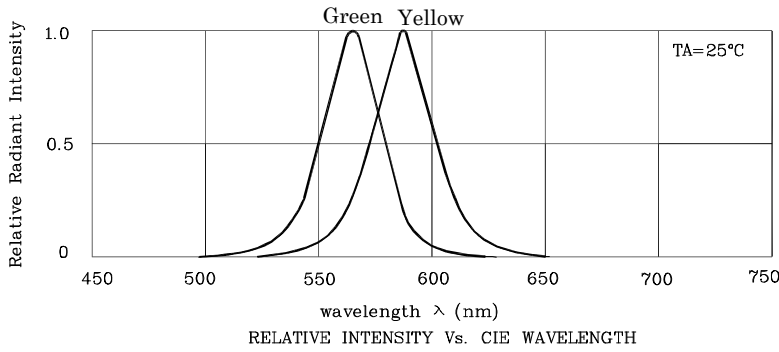
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		Green (GaP)	Yellow (GaAsP/ GaP)	Unit
Forward Current	I_F	25	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	140	140	mA
Power Dissipation	P_D	62.5	75	mW
Operating Temperature	T_A	-40 ~ +85		°C
Storage Temperature	T_{stg}	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

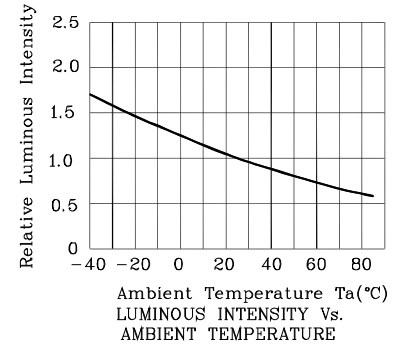
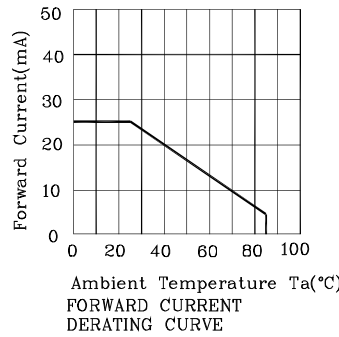
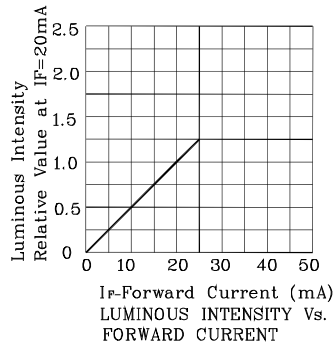
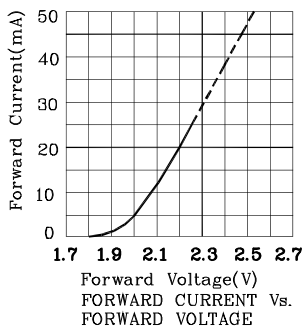
Operating Characteristics ($T_A=25^\circ\text{C}$)		Green (GaP)	Yellow (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2.2	2.1	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	2.5	V
Wavelength of Peak Emission CIE127-2007* (Typ.) ($I_F=20\text{mA}$)	λ_P	565*	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ($I_F=20\text{mA}$)	λ_D	568*	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	30	35	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	20	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* ($I_F=20\text{mA}$) mcd		Wavelength CIE127-2007* nm λ_P	Viewing Angle 20 1/2
				min.	typ.		
XLUGY37M	Green	GaP	White Diffused	6*	13*	565*	60°
	Yellow	GaAsP/GaP		4*	7*	590*	

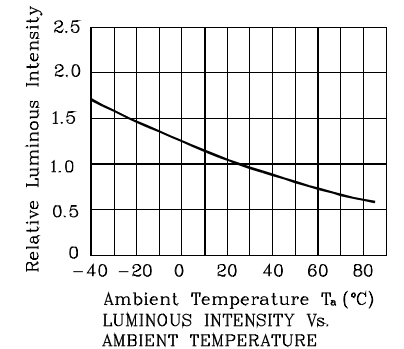
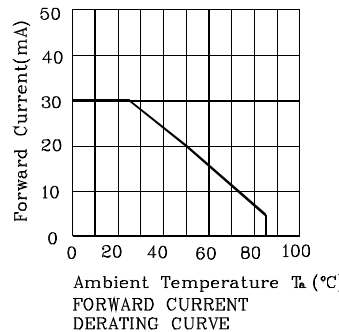
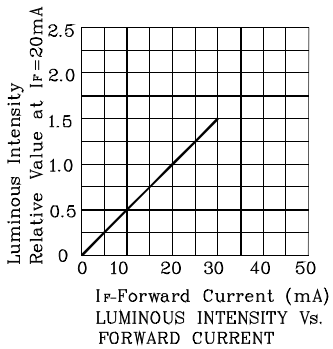
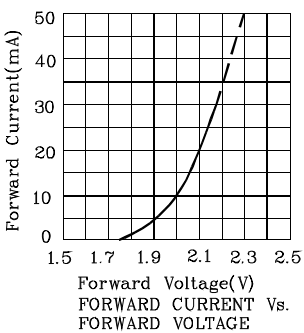
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



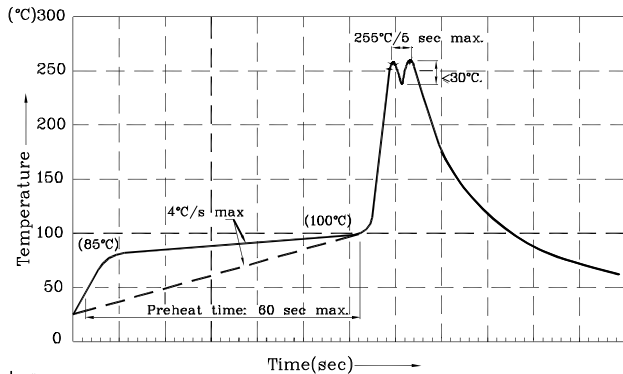
❖ Green



❖ Yellow



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



- Notes:
- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
 - 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
 - 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
 - 4.Fixtures should not incur stress on the component when mounting and during soldering process.
 - 5.SAC 305 solder alloy is recommended.
 - 6.No more than one wave soldering pass.

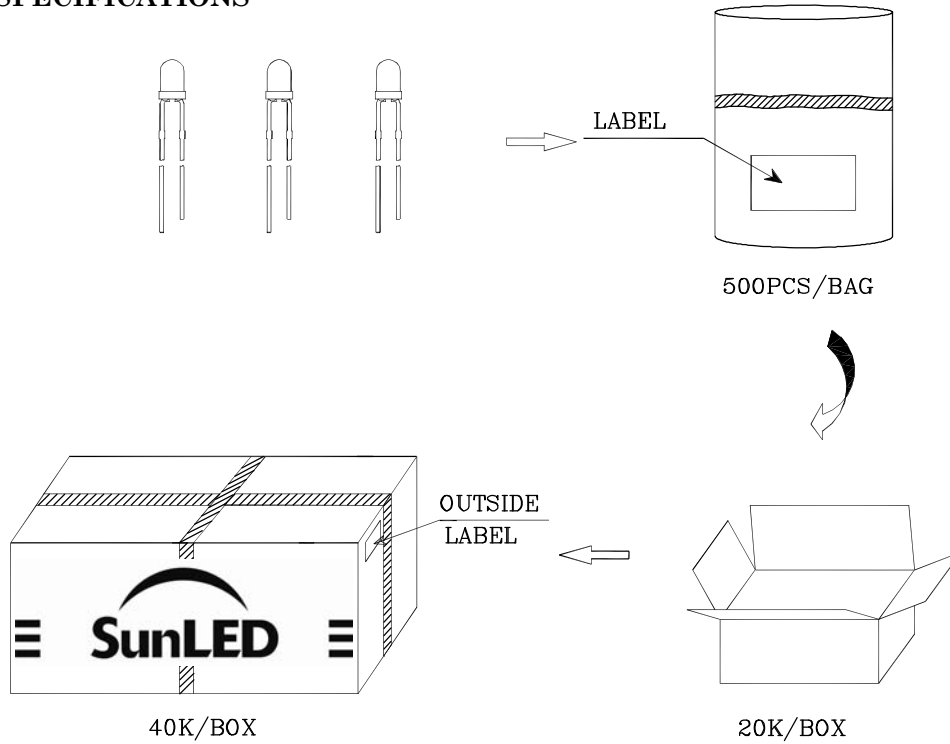
Remarks:


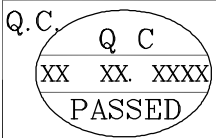

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



		
P/NO : XLxxx37x		
QTY : 500 pcs	CODE: XXX	
S/N : XX		
LOT NO:		
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX		
RoHS Compliant		

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2. Contents within this document are subject to improvement and enhancement changes without notice.
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